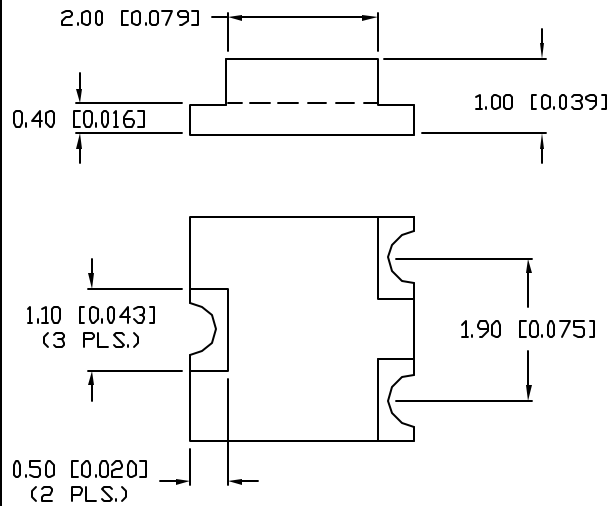
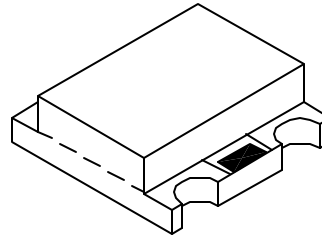
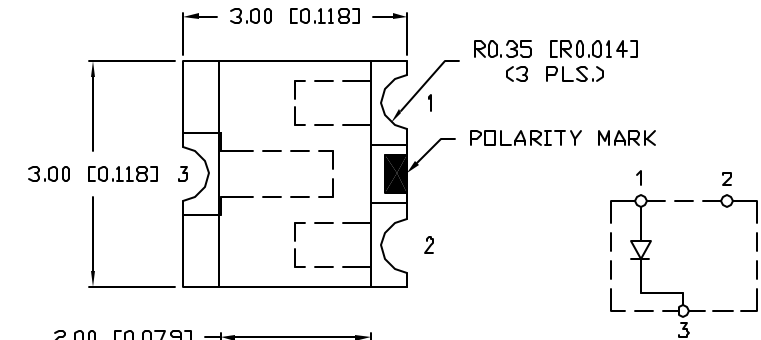


UNCONTROLLED DOCUMENT

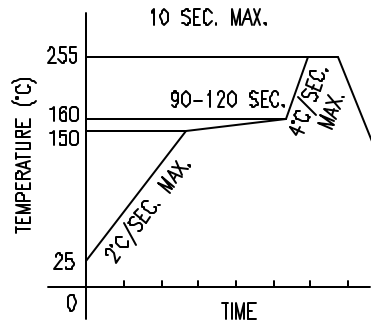
PART NUMBER
SML-LX15SIC-RP-TR

REV.

D

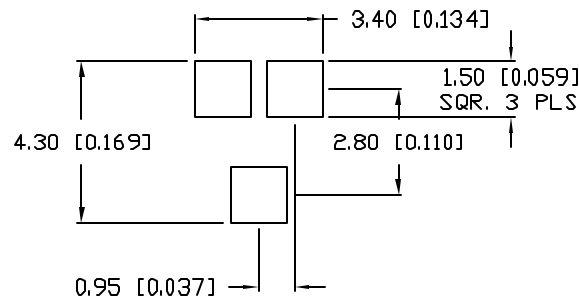


LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX. □ OPERATING, STORAGE TEMP.

RECOMMENDED PAD LAYOUT



REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10967.	3.14.03
B	E.C.N. #11010.	7.3.03
C	E.C.N. #11148.	11.30.05
D	E.C.N. #11361.	11.28.06

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		636		nm	
FORWARD VOLTAGE		2.0	2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY		60		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		140		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	160	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/°C
□ OPERATING, STORAGE TEMP.	-40 TO +85	°C

* $t < 10\mu\text{s}$

NOTES:

1. THE POLARITY MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.



CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS

UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (+0.039), XX=±0.5 (+0.020), XXX=±0.25 (+0.010), XXXX=±0.127 (+0.005), LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (+0.030), MIN= +DECIMAL PRECISION -0.00, MAX.= +0.00 -DECIMAL PRECISION

REV. D PART NUMBER SML-LX15SIC-RP-TR

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SOT-23 REPLACEMENT, SURFACE MOUNT LED,
636nm SUPER HIGH INTENSITY RED LED, REVERSE POLARITY,
WATER CLEAR LENS, TAPE AND REEL

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JC CHECKED BY: APPROVED BY: DATE: 11.28.06
PAGE: 1 OF 1
SCALE: N/A